

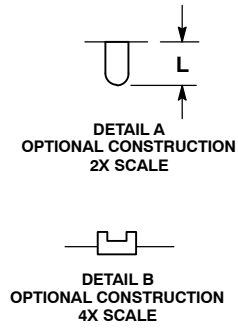
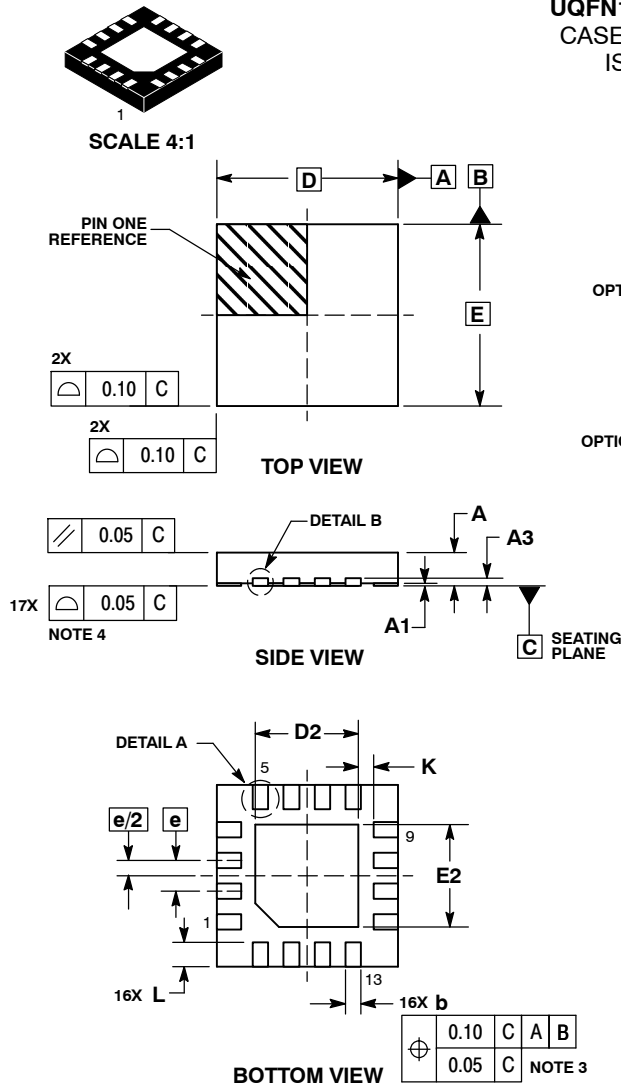
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



**UQFN16 3x3, 0.5P**  
CASE 523AF-01  
ISSUE A

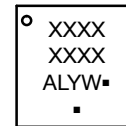
DATE 11 AUG 2008



- NOTES:
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  - CONTROLLING DIMENSION: MILLIMETERS.
  - DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
  - COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

| DIM | MILLIMETERS |      |
|-----|-------------|------|
|     | MIN         | MAX  |
| A   | 0.45        | 0.55 |
| A1  | 0.00        | 0.05 |
| A3  | 0.127 REF   |      |
| b   | 0.20        | 0.30 |
| D   | 3.00 BSC    |      |
| D2  | 1.60        | 1.80 |
| E   | 3.00 BSC    |      |
| E2  | 1.60        | 1.80 |
| e   | 0.50 BSC    |      |
| K   | 0.20        | ---  |
| L   | 0.30        | 0.50 |

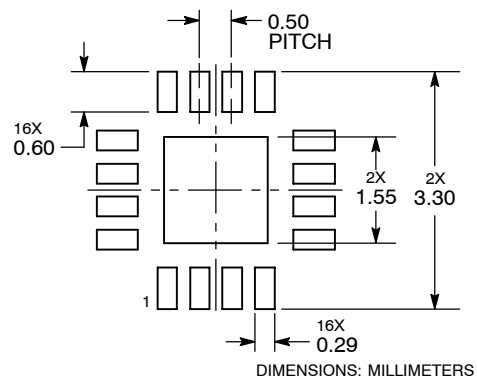
### GENERIC MARKING DIAGRAM\*



- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

|                         |                                  |  |
|-------------------------|----------------------------------|--|
| <b>DOCUMENT NUMBER:</b> | <b>98AON24478D</b>               | Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. |
| <b>STATUS:</b>          | <b>ON SEMICONDUCTOR STANDARD</b> |  |
| <b>NEW STANDARD:</b>    |                                  |  |
| <b>DESCRIPTION:</b>     | <b>UQFN16, 3X3, 0.5P</b>         | <b>PAGE 1 OF 2</b>   |

